

PCN Number:	20220927000.1		PCN Date:	September 27, 2022												
Title:	Qualification of GTBF as Additional Assembly Site for Select Devices															
Customer Contact:	PCN Manager	Dept:	Quality Services													
Proposed 1st Ship Date:	Dec 27, 2022	Sample Requests accepted until:	Oct 27, 2022*													
*Sample requests received after Oct 27, 2022 will not be supported.																
Change Type:																
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site											
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material											
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process											
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site											
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials											
				<input type="checkbox"/>	Wafer Fab Process											
PCN Details																
Description of Change:																
Texas Instruments Incorporated is announcing the qualification GTBF as an Additional Assembly Site for select devices listed in the "Product Affected" Section. Current assembly sites and Material differences are as follows.																
<table border="1"> <thead> <tr> <th>Assembly Site</th> <th>Assembly Site Origin</th> <th>Assembly Country Code</th> <th>Assembly Site City</th> </tr> </thead> <tbody> <tr> <td>Carsem (M)</td> <td>CAR</td> <td>MYS</td> <td>Ipoh</td> </tr> <tr> <td>GTBF</td> <td>GTF</td> <td>CHN</td> <td>Dong Guan</td> </tr> </tbody> </table>					Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly Site City	Carsem (M)	CAR	MYS	Ipoh	GTBF	GTF	CHN	Dong Guan
Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly Site City													
Carsem (M)	CAR	MYS	Ipoh													
GTBF	GTF	CHN	Dong Guan													
Material Differences:																
	Carsem (M)		GTBF													
Mount Compound	SID# 433987		SID# EY0000006													
Mold Compound	SID# MP180S, SID#434959		SID# EN0000030													
Reason for Change:																
Continuity of Supply																
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																
None																
Impact on Environmental Ratings																
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.																
<table border="1"> <thead> <tr> <th>RoHS</th> <th>REACH</th> <th>Green Status</th> <th>IEC 62474</th> </tr> </thead> <tbody> <tr> <td><input checked="" type="checkbox"/> No Change</td> <td><input checked="" type="checkbox"/> No Change</td> <td><input checked="" type="checkbox"/> No Change</td> <td><input checked="" type="checkbox"/> No Change</td> </tr> </tbody> </table>					RoHS	REACH	Green Status	IEC 62474	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change				
RoHS	REACH	Green Status	IEC 62474													
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change													
Changes to product identification resulting from this PCN:																

Assembly Site		
Carsem (M)	Assembly Site Origin (22L)	ASO: CAR
GTBF (Great Team Backend Foundry)	Assembly Site Origin (22L)	ASO: GTF

Sample product shipping label (not actual product label)





MADE IN: Malaysia
 2DC: 2Q:
 MSL 2 / 260C / 1 YEAR SEAL DT
 MSL 1 / 235C / UNLIM 03/29/04
 OPT:
 ITEM: 39
 LBL: 5A (L)T0:1750

(1P) SN74LS07NSR
 (Q) 2000 (D) 0336
 (31T) LOT: 3959047MLA
 (4W) TKY (1T) 7523483S12
 (P)
 (2P) REV: (V) 0033317
 (20L) CSO: SHE (21L) CCO: USA
 (22L) ASO: MLA (23L) ACO: MYS

Product Affected:

BUF634F/500	REG103FA-5KTTT	REG104FA-A/500	TPS78618KTTR
BUF634F/500E3	REG103FA-5KTTTG3	REG104FA-A/500G3	TPS78618KTTRG3
BUF634FKTTT	REG103FA-A/500	SN1203007KTT	TPS78625KTTR
BUF634FKTTTE3	REG103FA-AKTTT	TPS72501KTTR	TPS78628KTTT
BUF634T	REG104FA-2.5KTTT	TPS72501KTTRG3	TPS78630KTTT
BUF634TG3	REG104FA-2.5KTTTG3	TPS72525KTTR	TPS78633KTTR
REG103FA-2.5KTTT	REG104FA-3.3/500	TPS72525KTTRG3	TPS78633KTTRG3
REG103FA-2.5KTTTG3	REG104FA-5/500	TPS78601KTTR	
REG103FA-3.3KTTT	REG104FA-5/500G3	TPS78601KTTRG3	

Qualification Report

Approval Date: 25-August-2022

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TPS75901KC	Qual Device: UCC383TDTR-3
PC	Preconditioning	Level 2 - 260C	-	3/462/0
UHA ST	Unbiased HAST, 130C	96 Hours	-	3/231/0
TC	Temperature Cycle, -65C/150C	500 Cycles	3/231/0	3/231/0
ED	Electrical Characterization	Three-temperature	-	1/30/0
LF	Lead Fatigue	Leads	-	3/66/0
LP	Lead Pull	Leads	-	3/66/0
LFA	Lead Finish Adhesion	Leads	-	3/45/0
SH	Solder Heat, 260C	10 seconds	-	3/66/0
SA	Salt Atmosphere	24 Hours	-	3/66/0
SD	Solderability, Pb	155C Dry Bake Precondition, Leads	3/66/0	3/66/0
SD	Solderability, Pb-free	155C Dry Bake Precondition, Leads	3/66/0	3/66/0
MSL	Moisture Sensitivity	Level 2 - 260C	-	3/36/0
MQ	Manufacturability (Assembly)	(per mfg. site specification)	3/PASS	3/PASS
DSS	Die Shear Strength	Die	3/30/0	3/30/0
PD	Physical Dimensions	(per mechanical drawing)	3/15/0	3/15/0
VM	Visual / Mechanical	(per mfg. site specification)	3/30/0	3/30/0
WBP	Bond Pull	Wires	3/228/0	3/228/0

Type	Test Name / Condition	Duration	Qual Device: TPS75901KC	Qual Device: UCC383TDTR-3
XRAY	X-ray	(top side only)	3/15/0	3/15/0

- Qual Device TPS75901KC is qualified at Not Classified
- Qual Device UCC383TDTR-3 is qualified at LEVEL2-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable.

- The following are equivalent Temperature Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
WW Change Management Team	PCN_ww_admin_team@list.ti.com

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